

**AMENDMENTS TO THE CLAIMS**

1. (Currently Amended) A testing method for testing contacting between a semiconductor chip and a test carrier, comprising:

loading the test carrier with the semiconductor chip such that contacts of the semiconductor chip directly contact corresponding contacts of the test carrier,

wherein the contacting between the test carrier and the semiconductor chip is tested immediately after the loading of the test carrier with the semiconductor chip, and

wherein the semiconductor chip comprises one or more contacting test contacts exclusively for testing the contacting between the semiconductor chip and the test carrier immediately after the loading of the test carrier with the semiconductor chip.

2. (Original) The testing method according to claim 1, further comprising connecting the carrier to a testing apparatus.

3. (Previously Presented) The testing method according to claim 2, wherein the carrier is connected to the testing apparatus, and the carrier is subsequently loaded with the semiconductor chip.

4. (Previously Presented) The testing method according to claim 1, wherein the carrier is loaded at a carrier loading station, and the contacting between the carrier and the semiconductor chip is tested before the carrier is transported to a further station.

5. (Previously Presented) The testing method according to claim 2, wherein the contacting between the carrier and the semiconductor chip is tested by the testing apparatus.

6. (Previously Presented) The testing method according to claim 5, wherein the testing apparatus is configured such that it tests the contacting between the carrier and the semiconductor chip, but not functioning of the semiconductor chip.

7. (Previously Presented) The testing method according to claim 1, wherein the contacting between the carrier and the semiconductor chip is tested less than 2 seconds after loading of the carrier with the semiconductor chip.

8. (Previously Presented) The testing method according to claim 1, further comprising determining during the testing of the contacting between the carrier and the semiconductor chip whether an electric contact has been established between a corresponding pad of the semiconductor chip and an assigned pad of the carrier after loading of the carrier with the semiconductor chip.

9. (Previously Presented) The testing method according to claim 1, further comprising determining during the testing of the contacting between the carrier and the semiconductor chip whether a respective electric contact has been established between a plurality of pads of the semiconductor chip and respectively assigned pads of the carrier after loading of the carrier with the semiconductor chip.

10. (Previously Presented) The testing method according to claim 8, wherein power of current flowing through the corresponding semiconductor chip pad is determined to find whether an electric contact has been established between a corresponding pad of the semiconductor chip and an assigned pad of the carrier.

11. (Previously Presented) The testing method according to claim 8, wherein an amount of voltage dropping across the corresponding semiconductor chip pad is determined to find whether an electric contact has been established between a corresponding pad of the semiconductor chip and an assigned pad of the carrier.

12. (Currently Amended) A testing system for testing contacting between a semiconductor chip and a carrier, comprising:

a testing apparatus to which a carrier can be connected, and which is configured such that a direct contacting between the carrier and the semiconductor chip is tested by the testing chip immediately after loading of the carrier with a semiconductor chip: and

one or more contacting test contacts exclusively to test the contacting between the semiconductor chip and the carrier immediately after the loading of the carrier with the semiconductor chip.

13. (Currently Amended) The testing system according to claim 12, wherein the testing apparatus performs the test after a signal is output ~~by a loading chip, the signal indicating which~~ indicates that the carrier was loaded with the semiconductor chip.

14. (Previously Presented) The testing system according to claim 12, further comprising a testing apparatus, the testing apparatus being configured such that contacting between the carrier and the semiconductor chip is tested immediately after loading of the carrier with the semiconductor chip.

15. (Previously Presented) The method according to claim 1, wherein the one or more contacting test contacts are not used during ordinary operation of the semiconductor chip.

16. (Previously Presented) The method according to claim 15, wherein the semiconductor chip further comprises at least one additional contact used during ordinary operation of the semiconductor chip.

17. (Previously Presented) The method according to claim 1, wherein the one or more contacting test contacts are not used for testing the functioning of the semiconductor chip.

18. (Previously Presented) The method according to claim 17, wherein the semiconductor chip further comprises at least one additional contact used for testing the functioning of the semiconductor chip.

19. (Previously Presented) The system according to claim 12, wherein the one or more contacting test contacts are not used during ordinary operation of the semiconductor chip.

20. (Previously Presented) The system according to claim 19, wherein the semiconductor chip further comprises at least one additional contact used during ordinary operation of the semiconductor chip.

21. (Previously Presented) The system according to claim 12, wherein the one or more contacting test contacts are not used for testing the functioning of the semiconductor chip.

22. (Previously Presented) The system according to claim 21, wherein the semiconductor chip further comprises at least one additional contact used for testing the functioning of the semiconductor chip.

23. (Previously Presented) The testing method according to claim 1, wherein the one or more contacting test contacts are provided on a bottom of the semiconductor chip.

24. (Previously Presented) The testing system according to claim 12, wherein the one or more contacting test contacts are provided on a bottom of the semiconductor chip.

25. (Previously presented) The testing method according to claim 1, wherein the test carrier is a TSOP test carrier.

26. (Previously presented) A testing system to test a contact between a semiconductor chip and a test carrier, comprising:  
a test carrier comprising a plurality of contacts,

wherein the test carrier is configured to receive a semiconductor chip comprising a plurality of contacts, such that contacts of the semiconductor chip directly contact the corresponding contacts of the test carrier,

wherein the contacting between the contacts of the test carrier and the contacts of the semiconductor chip may be tested immediately after the loading of the test carrier with the semiconductor chip, and

wherein at least one of the contacts of the test carrier is a contacting test contact exclusively for testing the contacting between the contacts of the semiconductor chip and the contacts of the test carrier.

27. (Previously presented) The testing system according to claim 26, wherein the test carrier is a TSOP test carrier.

28. (Previously presented) The testing system according to claim 26, further comprising a testing apparatus connected to the test carrier.

29. (Previously presented) The testing system according to claim 28, wherein the testing apparatus tests the contacting between the contacts of the semiconductor chip and the contacts of the test carrier.